



9/26/2011

**PRODUCT RELIABILITY REPORT  
FOR**

**MAXQ1050**

**Maxim Integrated Products**

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**Conclusion:**

The following qualification successfully meets the quality and reliability standards required of all Maxim products:

MAXQ1050

In addition, Maxim's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at <http://www.maxim-ic.com/TechSupport/dsreliability.html>.

**Device Description:**

A description of this device can be found in the product data sheet. You can find the product data sheet at [http://dbserv.maxim-ic.com/l\\_datasheet3.cfm](http://dbserv.maxim-ic.com/l_datasheet3.cfm).

**Reliability Derating:**

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

$$AfT = \exp((Ea/k) * (1/Tu - 1/Ts)) = tu/ts$$

AfT = Acceleration factor due to Temperature  
tu = Time at use temperature (e.g. 55°C)  
ts = Time at stress temperature (e.g. 125°C)  
k = Boltzmann's Constant (8.617 x 10<sup>-5</sup> eV/°K)  
Tu = Temperature at Use (°K)  
Ts = Temperature at Stress (°K)  
Ea = Activation Energy (e.g. 0.7 ev)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

$$AfV = \exp(B * (Vs - Vu))$$

AfV = Acceleration factor due to Voltage  
Vs = Stress Voltage (e.g. 7.0 volts)  
Vu = Maximum Operating Voltage (e.g. 5.5 volts)  
B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

$$Fr = X / (ts * AfV * AfT * N * 2)$$

X = Chi-Sq statistical upper limit  
N = Life test sample size

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

$$\text{MTTF} = 1/\text{Fr}$$

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

**FAILURE RATE:**                      **MTTF (YRS):**            **71046**            **FITS:**            **1.6**  
**DEVICE HOURS:**    **570269019**    **FAILS:**            **0**

Only data from Operating Life or similar stresses are used for this calculation.

The parameters used to calculate this failure rate are as follows:

**Cf: 60%**            **Ea: 0.7**            **B: 0**                      **Tu: 25 °C**            **Vu: 5.5 Volts**

The reliability data follows. At the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available and may contain some generic data. **Bold** Product Number denotes specific product data.

**Device Information:**

Process:                      TSMC 0.18um Mixed signal, Embedded Flash, General Purpose, Two Poly Five Metal, 1.8V/3.3V Polyimide - No  
Passivation:                SiO/SiN  
Die Size:                      127 x 129  
Number of Transistors:    3084863  
Interconnect:                Aluminum / 0.5% Copper  
Gate Oxide Thickness:    32 Å

**ESD HBM**

DESCRIPTION	DATE	CODE/PRODUCT/LOT	CONDITION	READPOIN	QTY	FAILS	FA#
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB JESD22-A114 HBM 500 VOLTS	1	PUL'S	5	0
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB JESD22-A114 HBM 1000 VOLTS	1	PUL'S	5	0
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB JESD22-A114 HBM 2000 VOLTS	1	PUL'S	5	0
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB JESD22-A114 HBM 4000 VOLTS	1	PUL'S	5	0
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB JESD22-A114 HBM 8000 VOLTS	1	PUL'S	5	5 No FA
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB HBM 6000 VOLTS	1	PUL'S	3	0
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB HBM 8000 VOLTS	1	PUL'S	3	0
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB HBM 10000 VOLTS	1	PUL'S	3	0
<b>Total:</b>						<b>5</b>	

**ESD IEC**

DESCRIPTION	DATE	CODE/PRODUCT/LOT	CONDITION	READPOIN	QTY	FAILS	FA#
ESD SENSITIVITY	1134	<b>MAXQ1050</b>	ZS123062AB IEC 61000-4-2 CONTACT 2000 VOLTS	10	PUL'S	3	0

ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 CONTACT 4000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 CONTACT 6000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 CONTACT 8000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 AIR 2000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 AIR 4000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 AIR 8000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 AIR 10000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 AIR 12000 VOLTS	10	PUL'S	3	0
ESD SENSITIVITY	1134	MAXQ1050	ZS123062AB	IEC 61000-4-2 AIR 15000 VOLTS	10	PUL'S	3	0
<b>Total:</b>								<b>0</b>

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#### LATCH-UP

DESCRIPTION	DATE	CODE/PRODUCT/LOT	CONDITION	READPOIN	QTY	FAILS	FA#
LATCH-UP I	1134	MAXQ1050	ZS123062AB	JESD78A, I-TEST 25C 100mA		6	0
LATCH-UP I	1134	MAXQ1050	ZS123062AB	JESD78A, I-TEST 25C 250mA		6	0
LATCH-UP V	1134	MAXQ1050	ZS123062AB	JESD78A, V-SUPPLY TEST 25C		6	0
<b>Total:</b>							<b>0</b>

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#### OPERATING LIFE

DESCRIPTION	DATE	CODE/PRODUCT/LOT	CONDITION	READPOIN	QTY	FAILS	FA#
HIGH TEMP OP LIFE	0814	MAXQ1103	QN089294A	125C, 3.6V (PSA) & 2.0V (PSB)	1000 HRS	77	0
HIGH TEMP OP LIFE	0828	MAXQ2010	QK086138C	125C, 3.6 VOLTS	1000 HRS	76	0
HIGH TEMP OP LIFE	0837	MAX2990	QN096322A	125C, 3.6V (PSA) & 2.0V (PSB)	1000 HRS	77	0
HIGH TEMP OP LIFE	0851	MAXQ3108	QJ091011AC	125C, 3.6 VOLTS	192 HRS	73	0
HIGH TEMP OP LIFE	0851	MAXQ610	QJ091123AB	125C, 3.6V (PSA) & 2.0V (PSB)	1000 HRS	77	0
HIGH TEMP OP LIFE	0852	MAXQ1850	QJ091074AA	125C, 3.6 VOLTS	192 HRS	75	0
HIGH TEMP OP LIFE	0909	MAXQ8913	NQQ8ZAD	125C, 3.6V (PSA) & 5.0V (PSB)	192 HRS	77	0
HIGH TEMP OP LIFE	0934	MAXQ1103	QN101437A	125C, 3.6V (PSA) & 2.0V (PSB)	192 HRS	77	0
HIGH TEMP OP LIFE	0951	DS26514	QX108235AB	125C, 2.0V (PSB) & 3.5V (PSA)	1000 HRS	45	0
HIGH TEMP OP LIFE	0953	DS26514	QX108235A	125C, 2.0V (PSB) & 3.5V (PSA)	1000 HRS	45	0
HIGH TEMP OP LIFE	0953	DS26514	QX108235A	125C, 2.0V (PSB) & 3.5V (PSA)	1000 HRS	45	0

HIGH TEMP OP LIFE	1011	MAXQ3103	QJ101246AB 125C, 3.6 VOLTS	192 HRS	48	0
HIGH TEMP OP LIFE	1011	MAXQ3103	QJ101246AB 125C, 3.6 VOLTS	1000 HRS	77	0
HIGH TEMP OP LIFE	1119	MAXQ1740	ZJ112746BA 125C, 3.6 VOLTS	192 HRS	48	0
HIGH TEMP OP LIFE	1134	<b>MAXQ1050</b>	ZS123062AB 125C, 5.5V (PSA) & 3.6V (PSB)	192 HRS	48	0

**Total: 0**

**FAILURE RATE:                    MTTF (YRS):                    71046                    FITS:                    1.6**  
**DEVICE HOURS:                    570269019                    FAILS:                    0**

For ESD HBM section last 3 line items 6000V, 8000V, 10000V, and for ESD IEC the stress was done on pins VBUS, DP & DM with respect to GND only (one at a time) with 1uF cap between VBUS to GND.